



DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled in:

METHOD FOR REDUCING FREE SURFACE ROUGHNESS OF A SEMICONDUCTOR WAFER

and for which a patent application:

- ☒ is attached hereto and includes amendment(s) filed on _____ (if applicable)
☐ was filed in the United States on as Application No. _____ (declaration not accompanying application) with amendment(s) filed on _____ (if applicable)
☐ was filed as PCT international Application No. _____ on _____ and was amended under PCT Article 19 on _____ (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified application, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

EARLIEST FOREIGN APPLICATION(S), IF ANY, FILED PRIOR TO THE FILING DATE OF THE APPLICATION			
APPLICATION NUMBER	COUNTRY	DATE OF FILING (day, month, year)	PRIORITY CLAIMED
0108859	French	July 4, 2001	<input checked="" type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below.

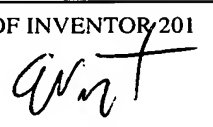
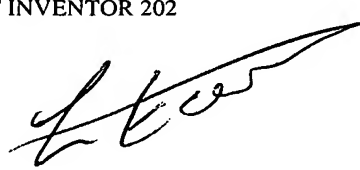
PROVISIONAL APPLICATION NUMBER	FILING DATE

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

NON-PROVISIONAL APPLICATION NO.	FILING DATE	STATUS		
		PATENTED	PENDING	ABANDONED
PCT/FR02/02341	July 4, 2002		X	

* for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

2 0 1	FULL NAME OF INVENTOR	LAST NAME NEYRET	FIRST NAME Eric	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY Sassenage	STATE OR FOREIGN COUNTRY France	COUNTRY OF CITIZENSHIP France	
	POST OFFICE ADDRESS	STREET 2, rue Lesdiguières	CITY Sassenage	STATE OR COUNTRY France	ZIP CODE 38360
		SIGNATURE OF INVENTOR 201 		DATE 01/12/04	
2 0 2	FULL NAME OF INVENTOR	LAST NAME ECARNOT	FIRST NAME Ludovic	MIDDLE NAME	
	RESIDENCE & CITIZENSHIP	CITY Varces	STATE OR FOREIGN COUNTRY France	COUNTRY OF CITIZENSHIP France	
	POST OFFICE ADDRESS	STREET 10 Lotissement le Nivelon	CITY Varces	STATE OR COUNTRY France	ZIP CODE 38760
		SIGNATURE OF INVENTOR 202 		DATE 01/12/04	



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Eric NEYRET et al.

Application No.: To be assigned

Group Art Unit:

Filing Date:

Examiner:

For: METHOD FOR REDUCING FREE SURFACE
ROUGHNESS OF A SEMICONDUCTOR
WAFER

Attorney Docket No.: 4717-8300

**POWER OF ATTORNEY BY ASSIGNEE
AND EXCLUSION OF INVENTOR(S) UNDER 37 C.F.R. 3.71**

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

The undersigned assignee of the entire interest in the above-identified subject application hereby appoints Allan A. Fanucci (Reg. No. 30,256) and Daniel J. Hulseberg (Reg. No. 36,554) of WINSTON & STRAWN LLP (Customer No. 28765) to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith.

Please direct all correspondence for this application to Customer No. 28765 to the attention of Allan A. Fanucci (telephone 212-294-3311, facsimile 212-294-4700).

An assignment of the entire interest in the above-identified subject application is submitted herewith for recording and a copy is attached. The undersigned has reviewed this assignment and, to the best of his knowledge, title is in the assignee seeking to take action in this application and that he is empowered to act on its behalf.

ASSIGNEE: S.O.I. TEC SILICON ON INSULATOR TECHNOLOGIES S.A.

Signature: *[Signature]*

Date of Signature: Jun 12th 2004

Typed Name: E. HUYGHE

Position/Title: IP Manager

Address: Parc Technologique des Fontaines
38126 Crollec CEDEX FRANCE

ASSIGNMENT

WHEREAS, WE,

Eric NEYRET, a citizen of France, residing at
2, rue Lesdiguieres, 38360 Sassenage, France; and

Ludovic ECARNOT, a citizen of France, residing at
10 Lotissement le Nivelon, 38760 Varcès, France,

ASSIGNORS, are the inventors of the invention entitled: **METHOD FOR REDUCING FREE SURFACE ROUGHNESS OF A SEMICONDUCTOR WAFER**, for which we have executed an application for a Patent of the United States

- ☒ which is identified by Docket No. 4717-8300
☐ which was filed on _____ as Application No. _____

WHEREAS, **S.O.I. TEC SILICON ON-INSULATOR TECHNOLOGIES**, a French corporate body having a place of business at Parc Technologique des Fontaines, F-38190 Bernin, France, ASSIGNEE, is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to each inventor in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, each ASSIGNOR has sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, their entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof;

And each ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument;

And each ASSIGNOR hereby covenants and agrees that they have the full right to convey the entire interest herein assigned, and that they have not executed, and will not execute, any agreement in conflict herewith;

And each ASSIGNOR hereby further covenants and agrees that they will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any

facts known to them respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention;

And each ASSIGNOR hereby authorizes the ASSIGNEE's patent attorney to complete this form by the addition of the application number, application filing date, and attorney docket number, if necessary.

In witness whereof, each inventor has affixed their signature.

Date Jan 12th, 2004



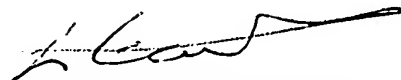
Eric NEYRET

On January 12th, 2004, before me, E. HUYGHE,
Witness, appeared **Eric NEYRET**, to me known and known to me to be the person of that name, who signed the foregoing instrument, and acknowledged the same to be his/her free act and deed.



Witness

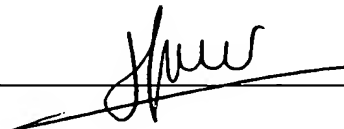
Date Jan 12th, 2004



Ludovic ECARNOT

On January 12th, 2004, before me, E. HUYGHE,
Witness, appeared **Ludovic ECARNOT**, to me known and known to me to be the person of that name, who signed the foregoing instrument, and acknowledged the same to be his/her free act and deed.

Date Jan 12th, 2004



Witness